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RESPONSE UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP 1765
LA
8/21/02

PATENT
Attorney Docket No. 98124x205487

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Wang et al.

Art Unit: 1765

Application No. 09/636,161

Examiner: Lynette T. Umez-Eronini

Filed: August 10, 2000

For: POLISHING SYSTEM AND METHOD
OF ITS USE

RESPONSE TO OFFICE ACTION

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AUG 22 2002

TC 1700

Commissioner for Patents
Box AF
Washington, D.C. 20231

Dear Sir:

In response to the Office Action dated June 18, 2002, please enter the following amendments and consider the following remarks.

AMENDMENTS

IN THE CLAIMS:

Please cancel claims 7, 10-15, and 36-39 without prejudice or disclaimer of the subject matter contained therein.

Please replace the indicated claims as follows:

1. (Amended) A system for polishing one or more layers of a multi-layer substrate that includes a first metal layer and a second layer comprising (i) a liquid carrier, (ii) at least one oxidizing agent, (iii) at least one polishing additive that increases the rate at which the system polishes at least one layer of the substrate, wherein the polishing additive is selected from the group consisting of pyrophosphates, condensed phosphates, diphosphonic acids, tri-phosphonic acids, poly-phosphonic acids, phosphonoacetic acids and salts thereof, aminoethylethanolamine, polyethyleneimine, amino alcohols, amides, imines, imino acids, nitriles, nitros, thioesters, thioethers, carbothiolic acids, carbothionic acids, thiocarboxylic